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#### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "[Embedded - Microcontrollers](#)"

##### Details

Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	59
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21368snfp-30">https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21368snfp-30</a>

**Table 1.2 Specifications (2)**

Item	Function	Description
Serial interface	UART0_0 and UART0_1	2 channels Clock synchronous serial I/O mode, clock asynchronous serial I/O mode
	UART2	1 channel Clock synchronous serial I/O mode, clock asynchronous serial I/O mode, I <sup>2</sup> C mode (I <sup>2</sup> C-bus), multiprocessor communication mode
Clock Synchronous serial interface	(SSU) SSU_0	1 channel (also used for the I <sup>2</sup> C bus)
	(I <sup>2</sup> C bus) I <sup>2</sup> C_0	1 channel (also used for the SSU)
LIN module	HW-LIN_0	Hardware LIN 1 channel (timer RJ_0, UART0_0, or UART0_1 used)
A/D converter		Resolution: 10 bits × 12 channels, sample and hold function, sweep mode
Comparator B		2 circuits
Touch Sensor control unit (TSCU)		System CH × 4, electrostatic capacitive touch detection × 28
CRC calculator		CRC-CCITT ( $X^{16} + X^{12} + X^5 + 1$ ), CRC-16 ( $X^{16} + X^{15} + X^2 + 1$ ) compliant
Flash memory		<ul style="list-style-type: none"> <li>• Program/erase voltage: VCC = 2.7 V to 5.5 V</li> <li>• Program/erase endurance: 10,000 times (data flash) 1,000 times (program ROM)</li> <li>• Program security: ROM code protect, ID code check</li> <li>• Debug functions: On-chip debug, on-board flash rewrite function</li> <li>• BGO (background operation) function (data flash)</li> </ul>
Operating frequency/ Power supply voltage		CPU clock = 20 MHz (VCC = 2.7 V to 5.5 V) CPU clock = 5 MHz (VCC = 1.8 V to 5.5 V)
Current consumption		<p>Typ. 6.5 mA (VCC = 5.0 V, f(XIN) = 20 MHz)      Typ. 3.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz)      Typ. 4.0 μA (VCC = 3.0 V, wait mode f(XCIN) = 32 kHz)      Typ. 2.2 μA (VCC = 3.0 V, stop mode)</p>
Operating ambient temperature		-20°C to 85°C (N version) -40°C to 85°C (D version) <sup>(1)</sup>
Package		64-pin LQFP Package code: PLQP0064KB-A (previous code: 64P6Q-A) Package code: PLQP0064GA-A (previous code: 64P6U-A)

Note:

- Specify the D version if it is to be used.

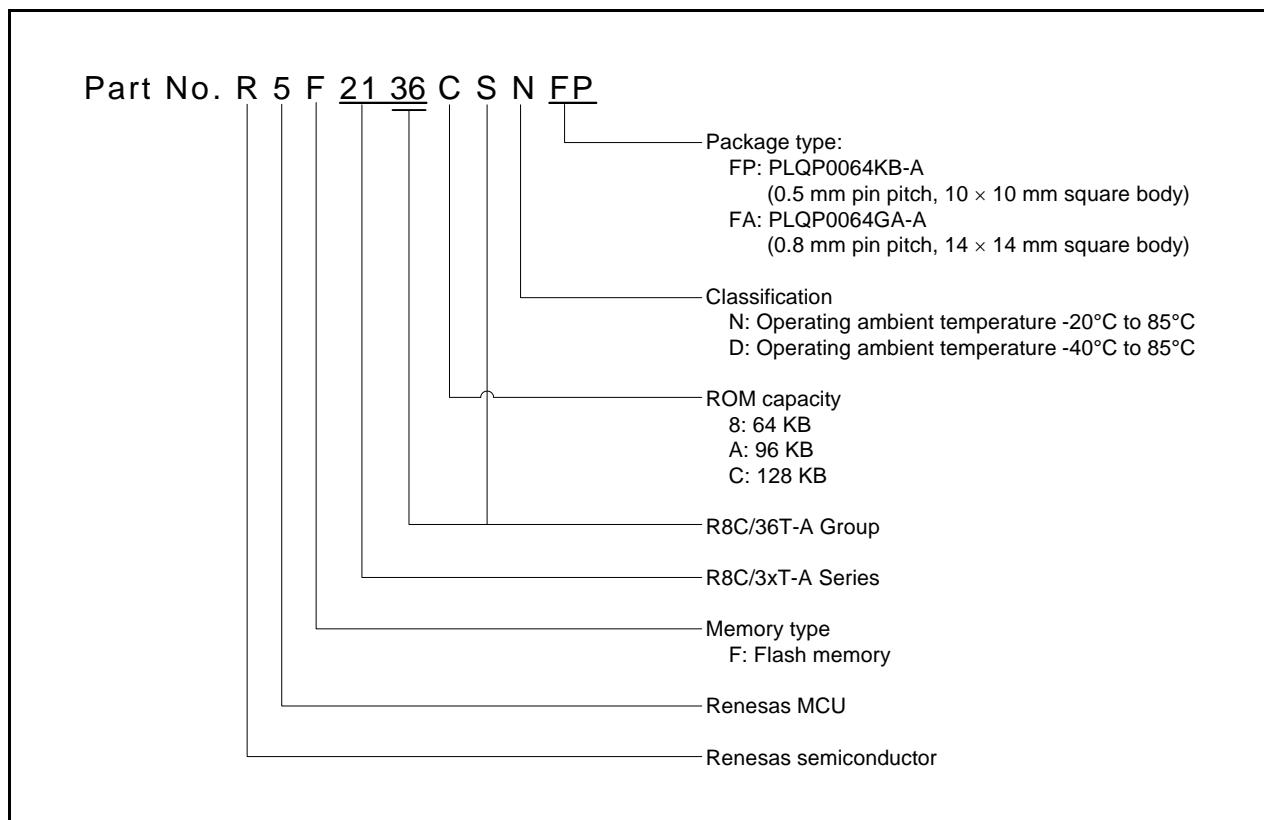
## 1.2 Product List

Table 1.3 lists product information. Figure 1.1 shows the Product Part Number Structure.

**Table 1.3 Product List**

**Current of Dec 2011**

Part No.	Internal ROM Capacity		Internal RAM Capacity	Package Type	Remarks
	Program ROM	Data Flash			
R5F21368SNFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A	N version
R5F2136ASNFP	96 Kbytes		8 Kbytes		
R5F2136CSNFP	128 Kbytes		10 Kbytes		
R5F21368SNFA	64 Kbytes		6 Kbytes		
R5F2136ASNFA	96 Kbytes		8 Kbytes		
R5F2136CSNFA	128 Kbytes		10 Kbytes		
R5F21368SDFP	64 Kbytes		6 Kbytes		
R5F2136ASDFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A	D version
R5F2136CSDFP	128 Kbytes		10 Kbytes		
R5F21368SDFA	64 Kbytes		6 Kbytes		
R5F2136ASDFA	96 Kbytes		8 Kbytes		
R5F2136CSDFA	128 Kbytes		10 Kbytes		



**Figure 1.1 Product Part Number Structure**

### 1.3 Block Diagram

Figure 1.2 shows the Block Diagram.

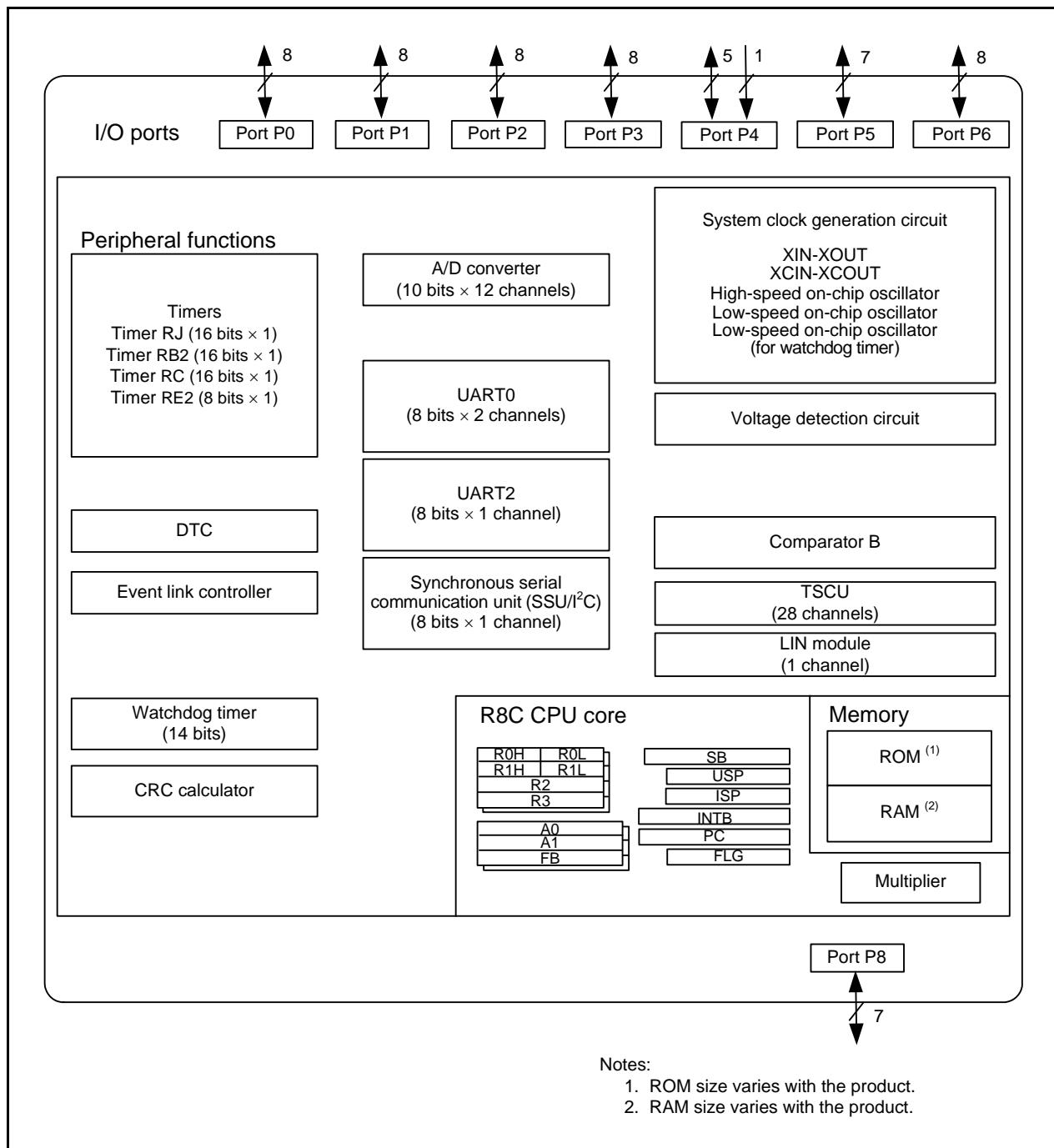


Figure 1.2 Block Diagram

**Table 1.5 Pin Name Information by Pin Number (SSU/I<sup>2</sup>C, Timer RJ, and Timer RB2)**

Port	Pin No.	SSU/I <sup>2</sup> C						Timer RJ		Timer RB2
		SCL_0	SDA_0	SSI_0	SCS_0	SSCK_0	SSO_0	TRJO_0	TRJIO_0	TRBO_0
P0_0	56									
P0_1	55									
P0_2	54									
P0_3	53									
P0_4	52									
P0_5	51									
P0_6	50									
P0_7	49									
P1_0	48									
P1_1	47									
P1_2	46									
P1_3	45									TRBO_0
P1_4	44									
P1_5	43									TRJIO_0
P1_6	42									
P1_7	41									
P2_0	27									
P2_1	26									
P2_2	25									
P2_3	24									
P2_4	23									
P2_5	22									
P2_6	21									
P2_7	20									
P3_0	1									TRJO_0
P3_1	29									
P3_2	64									TRJIO_0
P3_3	19				SCS_0					
P3_4	18			SSI_0						
P3_5	17	SCL_0				SSCK_0				
P3_6	28									
P3_7	16		SDA_0				SSO_0			
P4_2	2									
P4_3	4									
P4_4	5									
P4_5	40									
P4_6	9									
P4_7	7									
P5_0	15									
P5_1	14									
P5_2	13									
P5_3	12									
P5_4	11									
P5_6	63									
P5_7	62									
P6_0	61									
P6_1	60									
P6_2	59									
P6_3	58									
P6_4	57									
P6_5	39									
P6_6	38									
P6_7	37									
P8_0	36									
P8_1	35									
P8_2	34									
P8_3	33									
P8_4	32									
P8_5	31									
P8_6	30									

### 2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts. Interrupts are disabled when the I flag is 0, and are enabled when the I flag is 1. The I flag is set to 0 when an interrupt request is acknowledged.

### 2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is 0. USP is selected when the U flag is 1. The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction for a software interrupt numbered from 0 to 31 is executed.

### 2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns eight processor interrupt priority levels from 0 to 7. If a requested interrupt has higher priority than IPL, the interrupt is enabled.

### 2.8.10 Reserved Bit

The write value must be 0. The read value is undefined.

**Table 3.4 SFR Information (4) (1)**

Address	Symbol	Register Name	After Reset	Remarks
000BAh				
000BBh				
000BCh				
000BDh				
000BEh				
000BFh				
000C0h	U2MR	UART2 Transmit/Receive Mode Register	00h	
000C1h	U2BRG	UART2 Bit Rate Register	00h	
000C2h	U2TB	UART2 Transmit Buffer Register	00h	
000C3h			00h	
000C4h	U2C0	UART2 Transmit/Receive Control Register 0	00001000b	
000C5h	U2C1	UART2 Transmit/Receive Control Register 1	00000010b	
000C6h	U2RB	UART2 Receive Buffer Register	0000h	
000C7h				
000C8h	U2RXDF	UART2 Digital Filter Function Select Register	00h	
000C9h				
000CAh				
000CBh				
000CCh				
000CDh				
000CEh				
000CFh				
000D0h	U2SMR5	UART2 Special Mode Register 5	00h	
000D1h				
000D2h				
000D3h				
000D4h	U2SMR4	UART2 Special Mode Register 4	00h	
000D5h	U2SMR3	UART2 Special Mode Register 3	00h	
000D6h	U2SMR2	UART2 Special Mode Register 2	00h	
000D7h	U2SMR	UART2 Special Mode Register	00h	
000D8h				
000D9h				
000DAh				
000DBh				
000DCh				
000DDh				
000DEh				
000DFh				
000E0h	IICCR_0	I <sup>2</sup> C_0 Control Register	00001110b	
000E1h	SSBR_0	SS_0 Bit Counter Register	11111000b	
000E2h	SITDR_0	SI_0 Transmit Data Register	FFh	
000E3h			FFh	
000E4h	SIRDR_0	SI_0 Receive Data Register	FFh	
000E5h			FFh	
000E6h	SICR1_0	SI_0 Control Register 1	00h	
000E7h	SICR2_0	SI_0 Control Register 2	01111101b	
000E8h	SIMR1_0	SI_0 Mode Register 1	00010000b	
000E9h	SIER_0	SI_0 Interrupt Enable Register	00h	
000EAh	SISR_0	SI_0 Status Register	00h	
000EBh	SIMR2_0	SI_0 Mode Register 2	00h	
000EcH				
000EDh				
000EEh				
000EFh				
000F0h				
000F1h				
000F2h				
000F3h				
000F4h				
000F5h				
000F6h				
000F7h				
000F8h				
000F9h				

Note:

1. The blank areas are reserved. No access is allowed.

**Table 3.8 SFR Information (8) (1)**

Address	Symbol	Register Name	After Reset	Remarks
0023Ah	MSTCR2	Module Standby Control Register 2	00h	
0023Bh	MSTCR3	Module Standby Control Register 3	00h	
0023Ch	MSTCR4	Module Standby Control Register 4	00h	
0023Dh				
0023Eh				
0023Fh				
00240h				
00241h				
00242h				
00243h				
00244h				
00245h				
00246h				
00247h				
00248h				
00249h				
0024Ah				
0024Bh				
0024Ch				
0024Dh				
0024Eh				
0024Fh				
00250h				
00251h				
00252h	FST	Flash Memory Status Register	10000X00b	
00253h				
00254h	FMR0	Flash Memory Control Register 0	00h	
00255h	FMR1	Flash Memory Control Register 1	00h	
00256h	FMR2	Flash Memory Control Register 2	00h	
00257h				
00258h				
00259h				
0025Ah				
0025Bh				
0025Ch				
0025Dh				
0025Eh				
0025Fh				
00260h	AIADDR0L	Address Match Interrupt Address 0L Register	XXXXh	
00261h				
00262h	AIADDR0H	Address Match Interrupt Address 0H Register	0000XXXXb	
00263h	AIENO	Address Match Interrupt Enable 0 Register	00h	
00264h	AIADDR1L	Address Match Interrupt Address 1L Register	XXXXh	
00265h				
00266h	AIADDR1H	Address Match Interrupt Address 1H Register	0000XXXXb	
00267h	AIEN1	Address Match Interrupt Enable 1 Register	00h	
00268h				
00269h				
0026Ah				
0026Bh				
0026Ch				
0026Dh				
0026Eh				
0026Fh				
00270h				
00271h				
00272h				
00273h				
00274h				
00275h				
00276h				
00277h				
00278h				
00279h				
0027Ah				
0027Bh				
0027Ch				
0027Dh				
0027Eh				
0027Fh				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

**Table 3.9 SFR Information (9) (1)**

Address	Symbol	Register Name	After Reset	Remarks
00280h	DTCTL	DTC Activation Control Register	00h	
00281h				
00282h				
00283h				
00284h				
00285h				
00286h				
00287h				
00288h	DTCENO	DTC Activation Enable Register 0	00h	
00289h	DTCEN1	DTC Activation Enable Register 1	00h	
0028Ah	DTCEN2	DTC Activation Enable Register 2	00h	
0028Bh	DTCEN3	DTC Activation Enable Register 3	00h	
0028Ch				
0028Dh	DTCEN5	DTC Activation Enable Register 5	00h	
0028Eh	DTCEN6	DTC Activation Enable Register 6	00h	
0028Fh				
00290h	CRCSR	SFR Snoop Address Register	0000h	
00291h				
00292h	CRCMR	CRC Control Register	00h	
00293h				
00294h	CRCD	CRC Data Register	0000h	
00295h				
00296h	CRCIN	CRC Input Register	00h	
00297h				
00298h				
00299h				
0029Ah				
0029Bh				
0029Ch				
0029Dh				
0029Eh				
0029Fh				
002A0h	TRJ_0SR	Timer RJ_0 Pin Select Register	08h	
002A1h				
002A2h				
002A3h				
002A4h				
002A5h	TRCCLKSR	Timer RCCLK Pin Select Register	00h	
002A6h	TRC_0SR0	Timer RC_0 Pin Select Register 0	00h	
002A7h	TRC_0SR1	Timer RC_0 Pin Select Register 1	00h	
002A8h				
002A9h				
002AAh				
002ABh				
002ACh				
002ADh	TIMSR	Timer Pin Select Register	00h	
002AEh	U_0SR	UART0_0 Pin Select Register	00h	
002AFh	U_1SR	UART0_1 Pin Select Register	00h	
002B0h				
002B1h				
002B2h	U2SR0	UART2 Pin Select Register 0	00h	
002B3h	U2SR1	UART2 Pin Select Register 1	00h	
002B4h				
002B5h				
002B6h	INTSR0	INT Interrupt Input Pin Select Register 0	00h	
002B7h				
002B8h				
002B9h	PINSR	I/O Function Pin Select Register	00h	
002BAh				
002BBh				
002BCh				
002BDh				
002BEh	PMCSEL	Pin Assignment Select Register	00h	
002BFh				

Note:

1. The blank areas are reserved. No access is allowed.

**Table 3.10 SFR Information (10) (1)**

Address	Symbol	Register Name	After Reset	Remarks
002C0h	PUR0	Pull-Up Control Register 0	00h	
002C1h	PUR1	Pull-Up Control Register 1	00h	
002C2h	PUR2	Pull-Up Control Register 2	00h	
002C3h				
002C4h				
002C5h				
002C6h				
002C7h				
002C8h	P1DRR	Port P1 Drive Capacity Control Register	00h	
002C9h	P2DRR	Port P2 Drive Capacity Control Register	00h	
002CAh				
002CBh				
002CCh	DRR0	Drive Capacity Control Register 0	00h	
002CDh	DRR1	Drive Capacity Control Register 1	00h	
002CEh	DRR2	Drive Capacity Control Register 2	00h	
002CFh				
002D0h	VLT0	Input Threshold Control Register 0	00h	
002D1h	VLT1	Input Threshold Control Register 1	00h	
002D2h	VLT2	Input Threshold Control Register 2	00h	
002D3h				
002D4h				
002D5h				
002D6h				
002D7h				
002D8h				
002D9h				
002DAh				
002DBh				
002DCh				
002DDh				
002DEh				
002DFh				
002E0h	PORT0	Port P0 Register	XXh	
002E1h	PORT1	Port P1 Register	XXh	
002E2h	PD0	Port P0 Direction Register	00h	
002E3h	PD1	Port P1 Direction Register	00h	
002E4h	PORT2	Port P2 Register	XXh	
002E5h	PORT3	Port P3 Register	XXh	
002E6h	PD2	Port P2 Direction Register	00h	
002E7h	PD3	Port P3 Direction Register	00h	
002E8h	PORT4	Port P4 Register	XXh	
002E9h	PORT5	Port P5 Register	XXh	
002EAh	PD4	Port P4 Direction Register	00h	
002EBh	PD5	Port P5 Direction Register	00h	
002EcH	PORT6	Port P6 Register	XXh	
002EDh				
002EEh	PD6	Port P6 Direction Register	00h	
002EFh				
002F0h	PORT8	Port P8 Register	XXh	
002F1h				
002F2h	PD8	Port P8 Direction Register	00h	
002F3h				
002F4h				
002F5h				
002F6h				
002F7h				
002F8h				
002F9h				
002FAh				
002FBh				
002FCh				
002FDh				
002FEh				
002FFh				
00300h to 003FFh				

Note:

1. The blank areas are reserved. No access is allowed.

**Table 3.15 SFR Information (15) (1)**

Address	Symbol	Register Name	After Reset	Remarks
06C90h	DTCCR10	DTC Control Register 10	XXh	
06C91h	DTBLS10	DTC Block Size Register 10	XXh	
06C92h	DTCCT10	DTC Transfer Count Register 10	XXh	
06C93h	DTRLD10	DTC Transfer Count Reload Register 10	XXh	
06C94h	DTSAR10	DTC Source Address Register 10	XXXXh	
06C95h				
06C96h	DTDAR10	DTC Destination Address Register 10	XXXXh	
06C97h				
06C98h	DTCCR11	DTC Control Register 11	XXh	
06C99h	DTBLS11	DTC Block Size Register 11	XXh	
06C9Ah	DTCCT11	DTC Transfer Count Register 11	XXh	
06C9Bh	DTRLD11	DTC Transfer Count Reload Register 11	XXh	
06C9Ch	DTSAR11	DTC Source Address Register 11	XXXXh	
06C9Dh				
06C9Eh	DTDAR11	DTC Destination Address Register 11	XXXXh	
06C9Fh				
06CA0h	DTCCR12	DTC Control Register 12	XXh	
06CA1h	DTBLS12	DTC Block Size Register 12	XXh	
06CA2h	DTCCT12	DTC Transfer Count Register 12	XXh	
06CA3h	DTRLD12	DTC Transfer Count Reload Register 12	XXh	
06CA4h	DTSAR12	DTC Source Address Register 12	XXXXh	
06CA5h				
06CA6h	DTDAR12	DTC Destination Address Register 12	XXXXh	
06CA7h				
06CA8h	DTCCR13	DTC Control Register 13	XXh	
06CA9h	DTBLS13	DTC Block Size Register 13	XXh	
06CAAh	DTCCT13	DTC Transfer Count Register 13	XXh	
06CABh	DTRLD13	DTC Transfer Count Reload Register 13	XXh	
06CACh	DTSAR13	DTC Source Address Register 13	XXXXh	
06CADh				
06CAEh	DTDAR13	DTC Destination Address Register 13	XXXXh	
06CAFh				
06CB0h	DTCCR14	DTC Control Register 14	XXh	
06CB1h	DTBLS14	DTC Block Size Register 14	XXh	
06CB2h	DTCCT14	DTC Transfer Count Register 14	XXh	
06CB3h	DTRLD14	DTC Transfer Count Reload Register 14	XXh	
06CB4h	DTSAR14	DTC Source Address Register 14	XXXXh	
06CB5h				
06CB6h	DTDAR14	DTC Destination Address Register 14	XXXXh	
06CB7h				
06CB8h	DTCCR15	DTC Control Register 15	XXh	
06CB9h	DTBLS15	DTC Block Size Register 15	XXh	
06CBAh	DTCCT15	DTC Transfer Count Register 15	XXh	
06CBBh	DTRLD15	DTC Transfer Count Reload Register 15	XXh	
06CBCh	DTSAR15	DTC Source Address Register 15	XXXXh	
06CBDh				
06CBEh	DTDAR15	DTC Destination Address Register 15	XXXXh	
06CBFh				
06CC0h	DTCCR16	DTC Control Register 16	XXh	
06CC1h	DTBLS16	DTC Block Size Register 16	XXh	
06CC2h	DTCCT16	DTC Transfer Count Register 16	XXh	
06CC3h	DTRLD16	DTC Transfer Count Reload Register 16	XXh	
06CC4h	DTSAR16	DTC Source Address Register 16	XXXXh	
06CC5h				
06CC6h	DTDAR16	DTC Destination Address Register 16	XXXXh	
06CC7h				
06CC8h	DTCCR17	DTC Control Register 17	XXh	
06CC9h	DTBLS17	DTC Block Size Register 17	XXh	
06CCAh	DTCCT17	DTC Transfer Count Register 17	XXh	
06CCBh	DTRLD17	DTC Transfer Count Reload Register 17	XXh	
06CCCCh	DTSAR17	DTC Source Address Register 17	XXXXh	
06CCDh				
06CCEh	DTDAR17	DTC Destination Address Register 17	XXXXh	
06CCFh				

X: Undefined

Note:

1. The blank areas are reserved. No access is allowed.

**Table 3.16 SFR Information (16) (1)**

Address	Symbol	Register Name	After Reset	Remarks
06CD0h	DTCCR18	DTC Control Register 18	XXh	
06CD1h	DTBLS18	DTC Block Size Register 18	XXh	
06CD2h	DTCTC18	DTC Transfer Count Register 18	XXh	
06CD3h	DTRLD18	DTC Transfer Count Reload Register 18	XXh	
06CD4h	DTSAR18	DTC Source Address Register 18	XXXXh	
06CD5h				
06CD6h	DTDAR18	DTC Destination Address Register 18	XXXXh	
06CD7h				
06CD8h	DTCCR19	DTC Control Register 19	XXh	
06CD9h	DTBLS19	DTC Block Size Register 19	XXh	
06CDAh	DTCTC19	DTC Transfer Count Register 19	XXh	
06CDBh	DTRLD19	DTC Transfer Count Reload Register 19	XXh	
06CDCh	DTSAR19	DTC Source Address Register 19	XXXXh	
06CDCh				
06CDEh	DTDAR19	DTC Destination Address Register 19	XXXXh	
06CDFh				
06CE0h	DTCCR20	DTC Control Register 20	XXh	
06CE1h	DTBLS20	DTC Block Size Register 20	XXh	
06CE2h	DTCTC20	DTC Transfer Count Register 20	XXh	
06CE3h	DTRLD20	DTC Transfer Count Reload Register 20	XXh	
06CE4h	DTSAR20	DTC Source Address Register 20	XXXXh	
06CE5h				
06CE6h	DTDAR20	DTC Destination Address Register 20	XXXXh	
06CE7h				
06CE8h	DTCCR21	DTC Control Register 21	XXh	
06CE9h	DTBLS21	DTC Block Size Register 21	XXh	
06CEAh	DTCTC21	DTC Transfer Count Register 21	XXh	
06CEBh	DTRLD21	DTC Transfer Count Reload Register 21	XXh	
06CECh	DTSAR21	DTC Source Address Register 21	XXXXh	
06CEDh				
06CEEh	DTDAR21	DTC Destination Address Register 21	XXXXh	
06CEFh				
06CF0h	DTCCR22	DTC Control Register 22	XXh	
06CF1h	DTBLS22	DTC Block Size Register 22	XXh	
06CF2h	DTCTC22	DTC Transfer Count Register 22	XXh	
06CF3h	DTRLD22	DTC Transfer Count Reload Register 22	XXh	
06CF4h	DTSAR22	DTC Source Address Register 22	XXXXh	
06CF5h				
06CF6h	DTDAR22	DTC Destination Address Register 22	XXXXh	
06CF7h				
06CF8h	DTCCR23	DTC Control Register 23	XXh	
06CF9h	DTBLS23	DTC Block Size Register 23	XXh	
06CFAh	DTCTC23	DTC Transfer Count Register 23	XXh	
06CFBh	DTRLD23	DTC Transfer Count Reload Register 23	XXh	
06CFCh	DTSAR23	DTC Source Address Register 23	XXXXh	
06CFDh				
06CFEh	DTDAR23	DTC Destination Address Register 23	XXXXh	
06CFFh				
06D00h to 06FFFh				

X: Undefined

Note:

- The blank areas are reserved. No access is allowed.

**Table 4.5 Flash Memory (Program ROM) Characteristics  
(V<sub>CC</sub> = 2.7 V to 5.5 V, T<sub>OPR</sub> = -20°C to 85°C (N version)/-40°C to 85°C (D version), unless otherwise specified)**

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance <sup>(1)</sup>		1,000 <sup>(2)</sup>	—	—	times
—	Byte program time (Program and erase endurance ≤ 100 times)		—	—	—	μs
—	Byte program time (Program and erase endurance ≤ 1,000 times)		—	—	—	μs
—	Word program time (Program and erase endurance ≤ 100 times)	T <sub>OPR</sub> = 25°C, V <sub>CC</sub> = 5.0 V	—	100	200	μs
—	Word program time (Program and erase endurance ≤ 100 times)		—	100	400	μs
—	Word program time (Program and erase endurance ≤ 1,000 times)		—	100	650	μs
—	Block erase time		—	0.3	4	s
t <sub>d(SR-SUS)</sub>	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	μs
—	Time from suspend until erase restart		—	—	30 + CPU clock × 1 cycle	μs
t <sub>d(CMDRST-READY)</sub>	Time from when command is forcibly terminated until reading is enabled		—	—	30 + CPU clock × 1 cycle	μs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		-20 (N ver.) -40 (D ver.)	—	85	°C
—	Data hold time <sup>(6)</sup>	Ambient temperature = 55°C <sup>(7)</sup>	20	—	—	year

Notes:

1. Definition of programming/erasure endurance  
The programming and erasure endurance is defined on a per-block basis.  
If the programming and erasure endurance is n (n = 100 or 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.  
However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
2. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
6. The data hold time includes time that the power supply is off or the clock is not supplied.
7. The data hold time includes 7,000 hours under an environment of ambient temperature 85°C.

**Table 4.12 Low-Speed On-Chip Oscillator Circuit Characteristics**  
**(Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = -20°C to 85°C (N version)/**  
**-40°C to 85°C (D version))**

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
fLOCO	Low-speed on-chip oscillator frequency		60	125	250	kHz
—	Oscillation stability time	Vcc = 5.0 V, Topr = 25°C	—	30	100	μs
—	Self power consumption at oscillation	Vcc = 5.0 V, Topr = 25°C	—	3	—	μA

**Table 4.13 Power Supply Circuit Characteristics**  
**(Measurement conditions: Vcc = 1.8 V to 5.5 V, Topr = -20°C to 85°C (N version)/**  
**-40°C to 85°C (D version))**

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
td(P-R)	Time for internal power supply stabilization during power-on <sup>(1)</sup>		—	—	2,000	μs

Note:

- Waiting time until the internal power supply generation circuit stabilizes during power-on.

**Table 4.16 DC Characteristics (3) [2.7 V ≤ V<sub>CC</sub> < 4.2 V]**  
**(Measurement conditions: V<sub>CC</sub> = 1.8 V to 5.5 V, T<sub>OPR</sub> = -20°C to 85°C (N version)/**  
**-40°C to 85°C (D version))**

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
V <sub>OH</sub>	Output high voltage Other than XOUT	Drive capacity is high	I <sub>OH</sub> = -5 mA	V <sub>CC</sub> - 0.5	—	Vcc
		Drive capacity is low	I <sub>OH</sub> = -1 mA	V <sub>CC</sub> - 0.5	—	Vcc
	XOUT		I <sub>OH</sub> = -200 μA	1.0	—	Vcc
V <sub>OL</sub>	Output low voltage Other than XOUT	Drive capacity is high	I <sub>OL</sub> = 5 mA	—	—	0.5
		Drive capacity is low	I <sub>OL</sub> = 1 mA	—	—	0.5
	XOUT		I <sub>OL</sub> = 200 μA	—	—	0.5
V <sub>T+</sub> -V <sub>T-</sub>	Hysteresis INT0 to INT4, KI0 to KI3, TRJIO_0, TRCCLK_0, TRCTRG_0, TRCIOA_0, TRCIOB_0, TRCIOC_0, TRCIOD_0, CLK_0, CLK_1, RXD_0, RXD_1, CTS2, SCL2, SDA2, CLK2, RXD2, SCL_0, SDA_0, SSI_0, SCS_0, SSCK_0, SSO_0			0.1	0.4	—
		RESET	V <sub>CC</sub> = 3.0 V	0.1	0.5	—
I <sub>IH</sub>	Input high current		V <sub>I</sub> = 3.0 V	—	—	1.0 μA
I <sub>IL</sub>	Input low current		V <sub>I</sub> = 0 V	—	—	-1.0 μA
R <sub>PULLUP</sub>	Pull-up resistance		V <sub>I</sub> = 0 V	42	84	168 kΩ
R <sub>IXIN</sub>	Feedback resistance	XIN		—	0.3	—
R <sub>IXCIN</sub>	Feedback resistance	XCIN		—	8	—
V <sub>RAM</sub>	RAM hold voltage		During stop mode	1.8	—	—

**Table 4.17 DC Characteristics (4) [2.7 V ≤ Vcc < 3.3 V]  
(Topr = -20°C to 85°C (N version)/-40°C to 85°C (D version), unless otherwise specified)**

Symbol	Parameter	Conditions							Standard (4)			Unit	
		Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.		
		XIN (2)	XCIN	High-Speed	Low-Speed								
Icc	Power supply current (1)	High-speed clock mode	10 MHz	Off	Off	125 kHz	No division	—	—	3.5	10	mA	
			10 MHz	Off	Off	125 kHz	Divide-by-8	—	—	1.5	7.5	mA	
		High-speed on-chip oscillator mode	Off	Off	20 MHz (3)	125 kHz	No division	—	—	7.0	15	mA	
			Off	Off	20 MHz (3)	125 kHz	Divide-by-8	—	—	3.0	—	mA	
			Off	Off	10 MHz (3)	125 kHz	No division	—	—	4.0	—	mA	
			Off	Off	10 MHz (3)	125 kHz	Divide-by-8	—	—	1.5	—	mA	
			Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1	—	1	—	mA	
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0	—	90	390	μA	
			Off	32 kHz	Off	Off	No division	FMR27 = 1 SVC0 = 0	—	80	400	μA	
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMSTP = 1 SVC0 = 0	Program operation on RAM Flash memory off	—	40	—	μA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	μA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	80	μA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	μA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6.0	μA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	μA

Notes:

1. Vcc = 2.7 V to 3.3 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.  
The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

**Table 4.19 DC Characteristics (6) [1.8 V ≤ Vcc < 2.7 V]  
(Topr = -20°C to 85°C (N version)/-40°C to 85°C (D version), unless otherwise specified)**

Symbol	Parameter	Conditions							Standard (4)			Unit	
		Oscillation		On-Chip Oscillator		CPU Clock	Low-Power-Consumption Setting	Other	Min.	Typ.	Max.		
		XIN (2)	XCIN	High-Speed	Low-Speed								
Icc	Power supply current (1)	High-speed clock mode	5 MHz	Off	Off	125 kHz	No division	—	—	2.2	—	mA	
		High-speed on-chip oscillator mode	5 MHz	Off	Off	125 kHz	Divide-by-8	—	—	0.8	—	mA	
		High-speed on-chip oscillator mode	Off	Off	5 MHz (3)	125 kHz	No division	—	—	2.5	10	mA	
		High-speed on-chip oscillator mode	Off	Off	5 MHz (3)	125 kHz	Divide-by-8	—	—	1.7	—	mA	
		Low-speed on-chip oscillator mode	Off	Off	4 MHz (3)	125 kHz	Divide-by-16	MSTIIC = 1 MSTTRC = 1	—	1	—	mA	
		Low-speed on-chip oscillator mode	Off	Off	Off	125 kHz	Divide-by-8	FMR27 = 1 SVC0 = 0	—	90	300	μA	
		Low-speed clock mode	Off	32 kHz	Off	Off	No division	FMR27 = 1 SVC0 = 0	—	80	350	μA	
		Wait mode	Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock operation	—	15	90	μA
			Off	Off	Off	125 kHz	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	4	80	μA
			Off	32 kHz	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 SVC0 = 1	While a WAIT instruction is executed Peripheral clock off	—	3.5	—	μA
		Stop mode	Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 25°C Peripheral clock off	—	2.2	6	μA
			Off	Off	Off	Off	—	VCA27 = 0 VCA26 = 0 VCA25 = 0 CM10 = 1	Topr = 85°C Peripheral clock off	—	30	—	μA

Notes:

1. Vcc = 1.8 V to 2.7 V, single-chip mode, output pins are open, and other pins are Vss.
2. XIN is set to square wave input.
3. fHOCO-F
4. The typical value (Typ.) indicates the current value when the CPU and the memory operate.  
The maximum value (Max.) indicates the current value when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

## 4.5 AC Characteristics

**Table 4.20 Timing Requirements of Clock Synchronous Serial I/O with Chip Select (during Master Operation)**  
**(Measurement conditions: V<sub>cc</sub> = 1.8 V to 5.5 V, T<sub>opr</sub> = -20°C to 85°C (N version)/ -40°C to 85°C (D version))**

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
tsUCYC	SSCK clock cycle time		4.00	—	—	tCyc (1)
t <sub>H</sub>	SSCK clock high width		0.40	—	0.60	tsUCYC
t <sub>L</sub>	SSCK clock low width		0.40	—	0.60	tsUCYC
t <sub>RISE</sub>	SSCK clock rising time	2.7 V ≤ V <sub>cc</sub> ≤ 5.5 V	—	—	0.50	tCyc (1)
		1.8 V ≤ V <sub>cc</sub> < 2.7 V	—	—	1.00	tCyc (1)
t <sub>FALL</sub>	SSCK clock falling time	2.7 V ≤ V <sub>cc</sub> ≤ 5.5 V	—	—	0.50	tCyc (1)
		1.8 V ≤ V <sub>cc</sub> < 2.7 V	—	—	1.00	tCyc (1)
t <sub>SU</sub>	SSI, SSO data input setup time	4.5 V ≤ V <sub>cc</sub> ≤ 5.5 V	60	—	—	ns
		2.7 V ≤ V <sub>cc</sub> < 4.5 V	70	—	—	ns
		1.8 V ≤ V <sub>cc</sub> < 2.7 V	100	—	—	ns
t <sub>H</sub>	SSI, SSO data input hold time	2.7 V ≤ V <sub>cc</sub> ≤ 5.5 V	2.00	—	—	tCyc (1)
		1.8 V ≤ V <sub>cc</sub> < 2.7 V	2.00	—	—	tCyc (1)
t <sub>LEAD</sub>	SCS-SCK output delay time		0.5 tsUCYC - 1 tCyc	—	—	ns
t <sub>LAG</sub>	SCK -SCS output valid time		0.5 tsUCYC - 1 tCyc	—	—	ns
t <sub>OD</sub>	SSO data output delay time	2.7 V ≤ V <sub>cc</sub> ≤ 5.5 V	—	—	30.00	ns
		1.8 V ≤ V <sub>cc</sub> < 2.7 V	—	—	1.00	tCyc (1)

Note:

1. 1tCyc = 1/f1 (s)

**Table 4.21 Timing Requirements of Clock Synchronous Serial I/O with Chip Select (during Slave Operation)**  
**(Measurement conditions: V<sub>cc</sub> = 1.8 V to 5.5 V, T<sub>opr</sub> = -20°C to 85°C (N version)/ -40°C to 85°C (D version))**

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
tsUCYC	SSCK clock cycle time		4.00	—	—	tCYC (1)
t <sub>H</sub>	SSCK clock high width		0.40	—	0.60	tsUCYC
t <sub>L</sub>	SSCK clock low width		0.40	—	0.60	tsUCYC
t <sub>RISE</sub>	SSCK clock rising time		—	—	1.00	μs
t <sub>FALL</sub>	SSCK clock falling time		—	—	1.00	μs
ts <sub>U</sub>	SSO data input setup time		10.00	—	—	ns
t <sub>H</sub>	SSO data input hold time		2.00	—	—	tCYC (1)
t <sub>LEAD</sub>	SCS setup time		1tCYC + 50	—	—	ns
t <sub>LAG</sub>	SCS hold time		1tCYC + 50	—	—	ns
t <sub>OD</sub>	SSI, SSO data output delay time	4.5 V ≤ V <sub>cc</sub> ≤ 5.5 V	—	—	60	ns
		2.7 V ≤ V <sub>cc</sub> < 4.5 V	—	—	70	ns
		1.8 V ≤ V <sub>cc</sub> < 2.7 V	—	—	100.00	ns
t <sub>SA</sub>	SSI slave access time	2.7 V ≤ V <sub>cc</sub> ≤ 5.5 V	—	—	1.5tCYC + 100	ns
		1.8 V ≤ V <sub>cc</sub> < 2.7 V	—	—	1.5tCYC + 200	ns
t <sub>OR</sub>	SSI slave out open time	2.7 V ≤ V <sub>cc</sub> ≤ 5.5 V	—	—	1.5tCYC + 100	ns
		1.8 V ≤ V <sub>cc</sub> < 2.7 V	—	—	1.5tCYC + 200	ns

Note:

1. 1tCYC = 1/f<sub>1</sub> (s)

**Table 4.24 Timing Requirements of Serial Interface  
(Internal clock selected as transfer clock (master communication))**

Symbol	Parameter	Standard						Unit	
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C			
		Min.	Max.	Min.	Max.	Min.	Max.		
td(C-Q)	TXDi output delay time	—	200	—	30	—	10	ns	
tsu(D-C)	RXDi input setup time (1)	150	—	120	—	90	—	ns	
th(C-D)	RXDi input hold time	90	—	90	—	90	—	ns	

i = 0 or 1

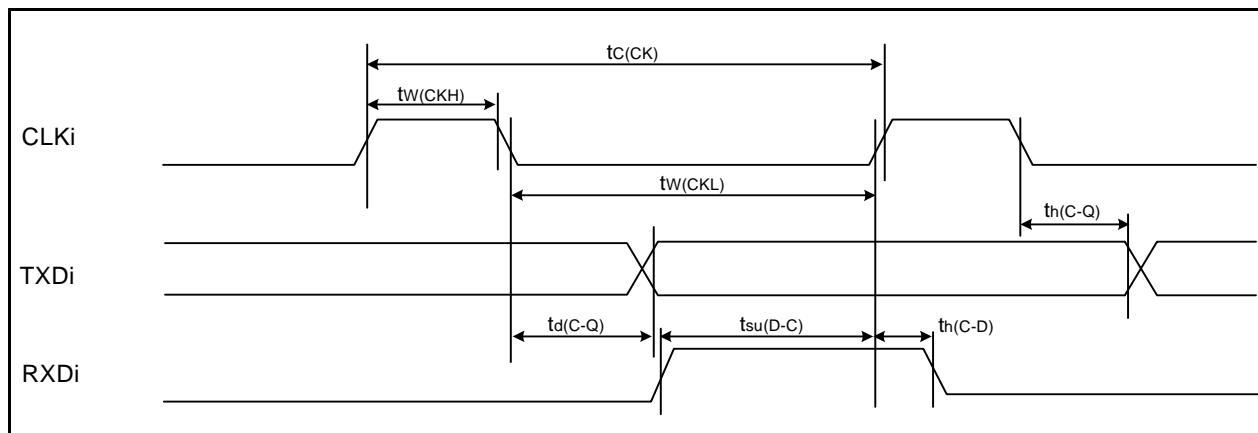
Note:

- External pin load condition CL = 30 pF

**Table 4.25 Timing Requirements of Serial Interface  
(External clock selected as transfer clock (slave communication))**

Symbol	Parameter	Standard						Unit	
		Vcc = 2.2 V, Topr = 25°C		Vcc = 3 V, Topr = 25°C		Vcc = 5 V, Topr = 25°C			
		Min.	Max.	Min.	Max.	Min.	Max.		
tc(CK)	CLKi input cycle time	800	—	300	—	200	—	ns	
tw(CKH)	CLKi input high width	400	—	150	—	100	—	ns	
tw(CKL)	CLKi input low width	400	—	150	—	100	—	ns	
td(C-Q)	TXDi output delay time	—	200	—	120	—	90	ns	
tsu(D-C)	RXDi input setup time	150	—	30	—	10	—	ns	
th(C-D)	RXDi input hold time	90	—	90	—	90	—	ns	

i = 0 or 1



**Figure 4.9 Input and Output Timing of Serial Interface (i = 0 or 1)**

## Appendix 1. Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Electronics website.

